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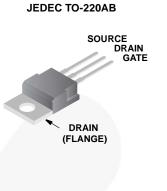
HUF75842P3

Data Sheet

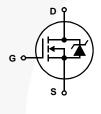
October 2013

N-Channel UltraFET Power MOSFET 150 V, 43 A, 42 mΩ

Packaging



Symbol



Features

• Ultra Low On-Resistance

- $r_{DS(ON)} = 0.042\Omega, V_{GS} = 10V$

- Simulation Models
 - Temperature Compensated PSPICE® and SABER™ Electrical Models
 - Spice and SABER Thermal Impedance Models
 - www.fairchildsemi.com
- Peak Current vs Pulse Width Curve
- UIS Rating Curve

Ordering Information

PART NUMBER	PACKAGE	BRAND
HUF75842P3	TO-220AB	75842P

Absolute Maximum Ratings $T_{C} = 25^{\circ}C$, Unless Otherwise Specified		
	HUF75842P3	UNITS
Drain to Source Voltage (Note 1)	150	V
Drain to Gate Voltage (R_{GS} = 20 $k\Omega$) (Note 1)	150	V
Gate to Source Voltage	±20	V
$ \begin{array}{l} \text{Drain Current} \\ \text{Continuous } (T_C = 25^{\circ}\text{C}, V_{GS} = 10\text{V}) (\text{Figure 2}) \dots I_D \\ \text{Continuous } (T_C = 100^{\circ}\text{C}, V_{GS} = 10\text{V}) (\text{Figure 2}) \dots I_D \\ \text{Pulsed Drain Current} \dots I_D \\ \end{array} $	43 30 Figure 4	A A
Pulsed Avalanche RatingUIS	Figures 6, 14, 15	
Power Dissipation PD Derate Above 25 ⁰ C	230 1.53	W W/ ^o C
Operating and Storage Temperature	-55 to 175	°C
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s	300 260	°C C
NOTES:		

1. $T_{J} = 25^{\circ}C$ to $150^{\circ}C$.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Product reliability information can be found at http://www.fairchildsemi.com/products/discrete/reliability/index.html For severe environments, see our Automotive HUFA series.

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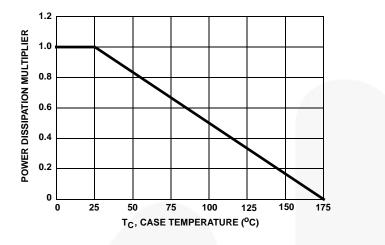
PARAMETER	SYMBOL	TES	CONDITIONS	MIN	ТҮР	МАХ	UNITS
OFF STATE SPECIFICATIONS		1		l			<u></u>
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V (Figure 11)		150	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 140V, V_{GS} = 0V$ $V_{DS} = 135V, V_{GS} = 0V, T_{C} = 150^{\circ}C$		-	-	1	μA
				-	-	250	μA
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V$		-	-	±100	nA
ON STATE SPECIFICATIONS	1						
Gate to Source Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250$	0μΑ (Figure 10)	2	-	4	V
Drain to Source On Resistance	rDS(ON)	I _D = 43A, V _{GS} = 10\	/ (Figure 9)	-	0.035	0.042	Ω
THERMAL SPECIFICATIONS						1	
Thermal Resistance Junction to Case	R _{θJC}	TO-220		-	-	0.65	°C/W
Thermal Resistance Junction to Ambient	R _{θJA}			-	-	62	°C/W
SWITCHING SPECIFICATIONS (V _{GS}	= 10V)			I			1
Turn-On Time	ton	V _{DD} = 75V, I _D = 43A		-	-	100	ns
Turn-On Delay Time	t _{d(ON)}	- V _{GS} = 10V, R _{GS} = 3.9Ω	-	13	-	ns	
Rise Time	t _r	— (Figures 18, 19) — —		-	53	-	ns
Turn-Off Delay Time	t _{d(OFF)}			-	47	-	ns
Fall Time	t _f			_	34	-	ns
Turn-Off Time	tOFF			-	-	120	ns
GATE CHARGE SPECIFICATIONS	1						
Total Gate Charge	Q _{g(TOT)}	$V_{GS} = 0V$ to 20V	V _{DD} = 75V,	-	144	175	nC
Gate Charge at 10V	Q _{g(10)}	$V_{GS} = 0V$ to 10V	── I _D = 43A, I _{g(REF)} = 1.0mA	-	77	90	nC
Threshold Gate Charge	Q _{g(TH)}	$V_{GS} = 0V$ to 2V	(Figures 13, 16, 17)	-	5.6	6.7	nC
Gate to Source Gate Charge	Q _{gs}	-		-	12	-	nC
Gate to Drain "Miller" Charge	Q _{gd}			-	30	-	nC
CAPACITANCE SPECIFICATIONS					, y		
Input Capacitance	C _{ISS}	$V_{DS} = 25V, V_{GS} = 0$	V,	-	2730	-	pF
Output Capacitance	C _{OSS}	f = 1MHz (Figure 12)		-	660	-	pF
Reverse Transfer Capacitance	C _{RSS}			-	230	1.	pF

Electrical Specifications $T_C = 25^{\circ}C$, Unless Otherwise Specified

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V _{SD}	I _{SD} = 43A	-	-	1.25	V
		I _{SD} = 22A	-	-	1.00	V
Reverse Recovery Time	t _{rr}	I _{SD} = 43A, dI _{SD} /dt = 100A/μs	-	-	190	ns
Reverse Recovered Charge	Q _{RR}	$I_{SD} = 43A$, $dI_{SD}/dt = 100A/\mu s$		-	1.08	μC

Typical Performance Curves





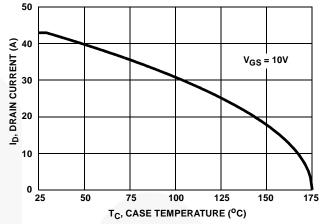
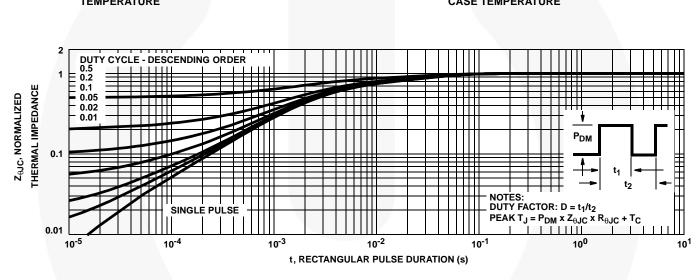


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE





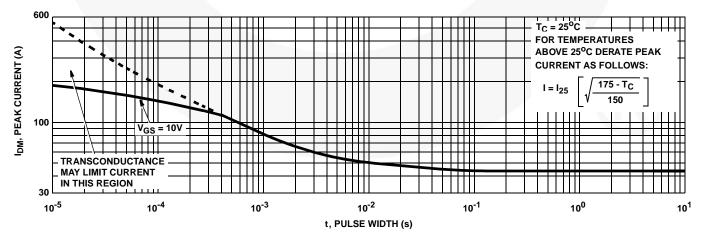


FIGURE 4. PEAK CURRENT CAPABILITY



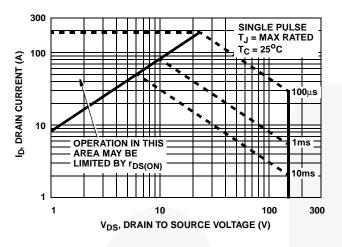


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA

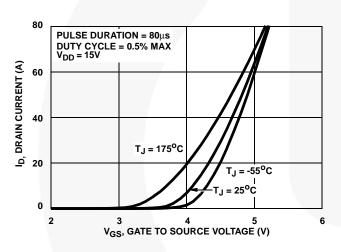
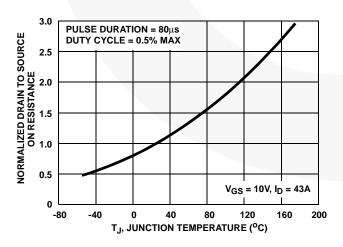
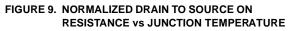
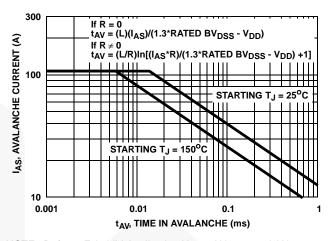


FIGURE 7. TRANSFER CHARACTERISTICS







NOTE: Refer to Fairchild Application Notes AN9321 and AN9322. FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING

CAPABILITY

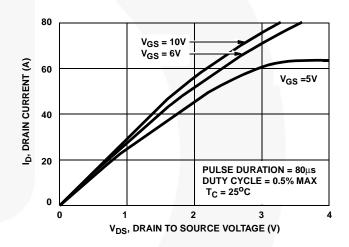


FIGURE 8. SATURATION CHARACTERISTICS

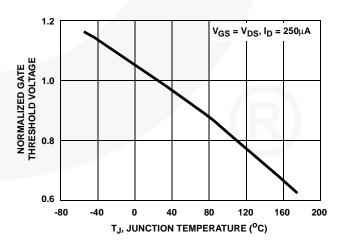
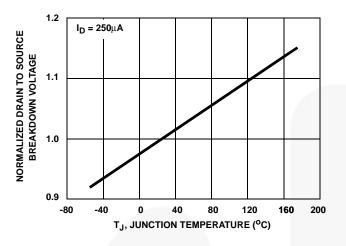
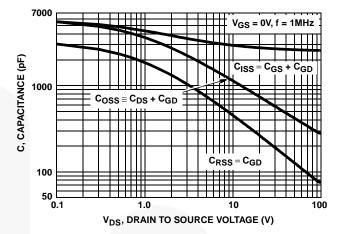


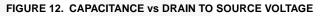
FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

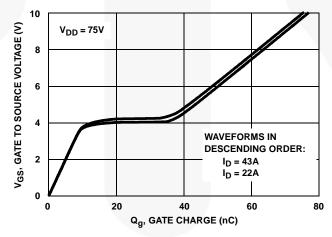
Typical Performance Curves (Continued)













Test Circuits and Waveforms

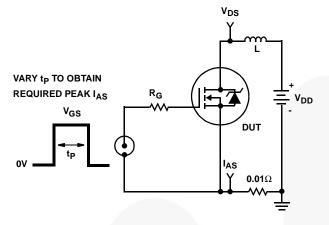


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

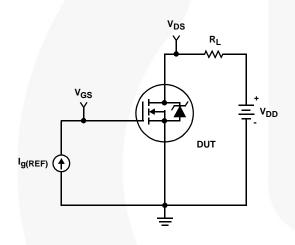


FIGURE 16. GATE CHARGE TEST CIRCUIT

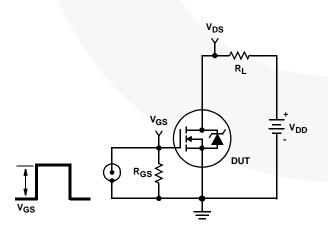


FIGURE 18. SWITCHING TIME TEST CIRCUIT

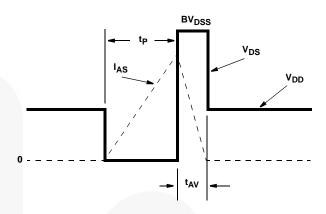
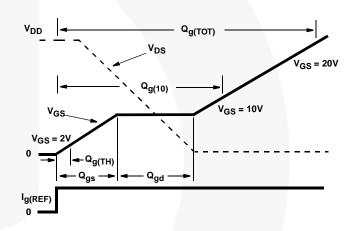


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS





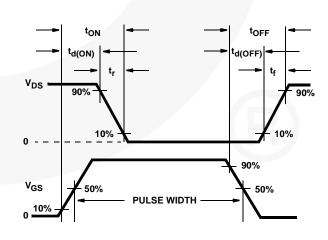
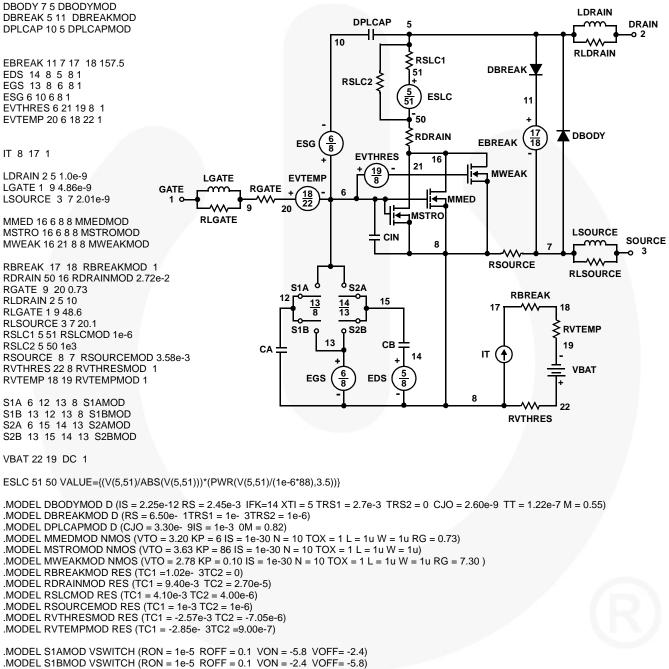


FIGURE 19. SWITCHING TIME WAVEFORM

PSPICE Electrical Model

.SUBCKT HUF75842 2 1 3 ; rev 13 October 1999

CA 12 8 4.10e-9 CB 15 14 4.10e-9 CIN 6 8 2.50e-9



.MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.8 VOFF = 0.5) .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.5 VOFF = -1.8)

.ENDS

NOTE: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.

SABER Electrical Model

REV 13 October 1999 template huf75842 n2,n1,n3 electrical n2,n1,n3 var i iscl d..model dbodymod = (is = 2.25e-12, cjo = 2.60e-9, tt = 1.22e-7, xti = 5, m = 0.55) d..model dbreakmod = () d..model dplcapmod = $(c_{ij} = 3.30e-9, is = 1e-30, m = 0.82)$ m..model mmedmod = (type=_n, vto = 3.20, kp = 6, is = 1e-30, tox = 1) m..model mstrongmod = (type=_n, vto = 3.63, kp = 86, is = 1e-30, tox = 1) m..model mweakmod = (type=_n, vto = 2.78, kp = 0.10, is = 1e-30, tox = 1) LDRAIN sw_vcsp..model s1amod = (ron = 1e-5, roff = 0.1, von = -5.8, voff = -2.4) DPLCAP 5 DRAIN sw_vcsp..model s1bmod = (ron =1e-5, roff = 0.1, von = -2.4, voff = -5.8) o 2 10 sw_vcsp..model s2amod = (ron = 1e-5, roff = 0.1, von = -1.8, voff = 0.5) RLDRAIN sw_vcsp..model s2bmod = (ron = 1e-5, roff = 0.1, von = 0.5, voff = -1.8) RSLC1 RDBREAK 51 c.ca n12 n8 = 4.10e-9 RSLC2 ≥ 72 c.cb n15 n14 = 4.10e-9 RDBODY ISCL c.cin n6 n8 = 2.50e-9 DBREAK 50 d.dbody n7 n71 = model=dbodymod RDRAIN 71 d.dbreak n72 n11 = model=dbreakmod 6 8 ESG 11 d.dplcap n10 n5 = model=dplcapmod EVTHRES 16 21 19 8 MWEAK i.it n8 n17 = 1 LGATE EVTEMP DBODY RGATE GATE 6 18 22 EBREAK I.Idrain n2 n5 = 1e-9 MMED I w 9 20 l.lgate n1 n9 = 4.86e-9 I ← _ MSTR RLGATE l.lsource n3 n7 = 2.01e-9 LSOURCE CIN SOURCE 8 m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u 3 m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u RSOURCE m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u RLSOURCE o S2A S1A res.rbreak n17 n18 = 1, tc1 = 1.02e-3, tc2 = 0 RBREAK <u>13</u> 8 15 <u>14</u> 13 res.rdbody n71 n5 = 2.45e-3, tc1 = 2.70e-3, tc2 = 0 17 18 res.rdbreak n72 n5 = 6.50e-1. tc1 = 1.0e-3. tc2 = 1.0e-6 res.rdrain n50 n16 = 2.72e-2, tc1 = 9.40e-3, tc2 = 2.70e-5 RVTEMP o S2B S1B res.rgate n9 n20 = 0.73 СВ 19 CA res.rldrain n2 n5 = 10 IT (♠ 14 res.rlgate n1 n9 = 48.6 VBAT res.rlsource n3 n7 = 20.1<u>6</u> 8 5 EGS EDS res.rslc1 n5 n51 = 1e-6, tc1 = 4.10e-3, tc2 = 4.00e-6 8 res.rslc2 n5 n50 = 1e3 22 res.rsource n8 n7 = 3.58e-3, tc1 = 1e-3, tc2 = 1e-6 RVTHRES res.rvtemp n18 n19 = 1, tc1 = -2.85e-3, tc2 = 9.00e-7 res.rvthres n22 n8 = 1, tc1 = -2.57e-3, tc2 = -7.05e-6 spe.ebreak n11 n7 n17 n18 = 157.5 spe.eds n14 n8 n5 n8 = 1 spe.egs n13 n8 n6 n8 = 1 spe.esg n6 n10 n6 n8 = 1 spe.evtemp n20 n6 n18 n22 = 1 spe.evthres n6 n21 n19 n8 = 1 sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod v.vbat n22 n19 = dc=1 equations { i (n51->n50) +=iscl iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/88))** 3.5))

SPICE Thermal Model

REV 13 October 1999

HUF75842T

CTHERM1 th 6 5.20e-3 CTHERM2 6 5 2.40e-2 CTHERM3 5 4 2.00e-2 CTHERM4 4 3 1.80e-2 CTHERM5 3 2 2.40e-2 CTHERM6 2 tl 1.80e-1

RTHERM1 th 6 1.00e-2 RTHERM2 6 5 2.00e-2 RTHERM3 5 4 6.40e-2 RTHERM4 4 3 1.00e-1 RTHERM5 3 2 1.56e-1 RTHERM6 2 tl 1.65e-1

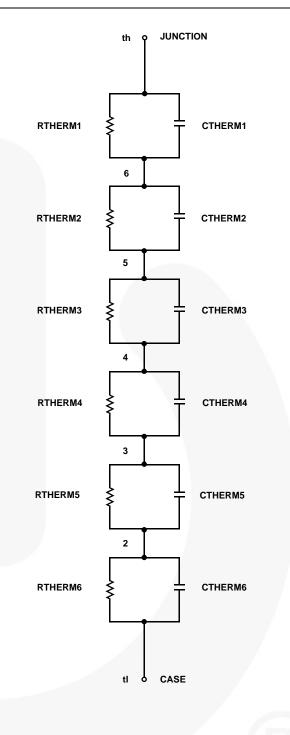
SABER Thermal Model

SABER thermal model HUF75842T

template thermal_model th tl thermal_c th, tl

ctherm.ctherm1 th 6 = 5.20e-3ctherm.ctherm2 6 5 = 2.40e-2ctherm.ctherm3 5 4 = 2.00e-2ctherm.ctherm4 4 3 = 1.80e-2ctherm.ctherm5 3 2 = 2.40e-2ctherm.ctherm6 2 tl = 1.80e-1

rtherm.rtherm1 th 6 = 1.00e-2rtherm.rtherm2 6 5 = 2.00e-2rtherm.rtherm3 5 4 = 6.40e-2rtherm.rtherm4 4 3 = 1.00e-1rtherm.rtherm5 3 2 = 1.56e-1rtherm.rtherm6 2 tl = 1.65e-1





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